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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

TAGUCHI ET AL

Application No.: 09/642,765

Art Unit: 1725

Filed: August 22, 2000

For: LEAD-FREE SOLDER PASTE FOR REFLOW SOLDERING

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Pursuant to the requirements of 37 CFR §§1.56 and 1.97, the attention of the Examiner is directed to the document listed on the attached Form PTO-1449. A copy of the listed document is attached. Neither this Statement nor the listing of this document on Form PTO-1449 is an admission that this document is prior art as to Applicants or a representation that a search has been made or that no more pertinent documents exist.

The attached document, Japanese Patent No. 3,027,441, is described on page 5 of the application as filed. The application which matured into this patent was published as Japanese Published Unexamined Patent Application No. 5-50286. An English

translation of the abstract of the published unexamined patent application is attached.

Applicants respectfully request that the attached document be considered by the Examiner and made of record in the referenced patent application.

Respectfully submitted,



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Signature Michael Tobias
Michael Tobias

Form PTO-1449 (Modified)

Atty Docket No.
1023/HiroseApplic. No.
09/642,765List of Patents and Publications
For Applicant's Information
Disclosure StatementApplicant
Taguchi et al(Use several sheets
if necessary)Filing Date
August 22, 2000Group
1725

U.S. PATENT DOCUMENTS

Exr's Initial	Document No.	Date	Name	Class	Sub class	Filing Date
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FOREIGN PATENT DOCUMENTS

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OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

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Examiner

Date Considered

EXAMINER: Initial if reference considered, no matter whether citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.